

TIM4101-3.0

Thermal Gap Filler Insulating Pad

Thermal gap filler has excellent flexibility insulation, compressibility and natural surface viscosity performances. It used to fill the gap and realize the heat transfer between the heating parts and cooling parts. It also has insulation and shock mitigation effects. Meanwhile, it can satisfy the design requirements for minitype and ultra-thin equipments with excellent manufacturability and practicability. With wide range of thickness, it is widely used in electronic products.

FEATURE

- Soft, excellent compression performance
- Low thermal resistance
- Being recognized as UL94 V-0
- Viscous surface
- Excellent insulation performance and thermal resistance
- Being to work under low pressure

APPLICATIONS

- Between chip and heat-dissipation modules
- Optoelectronic Industry
- Netcom products
- New energy battery and vehicles industry
- Household appliances
- Wearable equipments

This series of products are environmentally compliant with RoHS 2.0, halogen, and REACH standards.

STORAGE CONDITIONS: Storage in the darkness

STORAGE TEMPERATURE: ≤ 30 °C

STORAGE HUMIDITY: $\leq 70\%$

The height of the stacking should not be more than 7 layers and the total height should not be more than 1m.

SHELF LIFE:

Under storage conditions: 2 year

PROPERTIES

Item	Parameter	Unit	Test Method
Color	Sky Blue	-	Visual
Thickness Range	0.3 ~ 18	mm	ASTM D 374
Hardness Range	15-55	Shore C	ASTM D 2240
Density	3.01	g/cc	ASTM D 792
Tensile Strength	≥ 0.15	Mpa	ASTM D 412
Elongation	≥ 60	%	ASTM D 412
Compression Ratio	≥ 20 (@50Psi)	%	ASTM D 575
UL Certification	V-0,5V	-	UL94
Operating Temperature	-50~180	°C	IEC 60068 -2-14

THERMAL CHARACTERISTIC

Thermal Conductivity	3.0	W/m-K	ASTM D 5470
Thermal Resistance	≤ 0.9 (@20psi/1mm)	°C.cm ² /W	ASTM D 5470

ELECTRICAL PROPERTIES

Breakdown voltage	≥ 8	kV /mm	ASTM D 149
Volume resistivity	$\geq 10^{10}$	Ω .cm	ASTM D 257
Dielectric constant	≥ 2	@1MHz	ASTM D 150
Dielectric loss	≤ 0.1	@1MHz	ASTM D 150